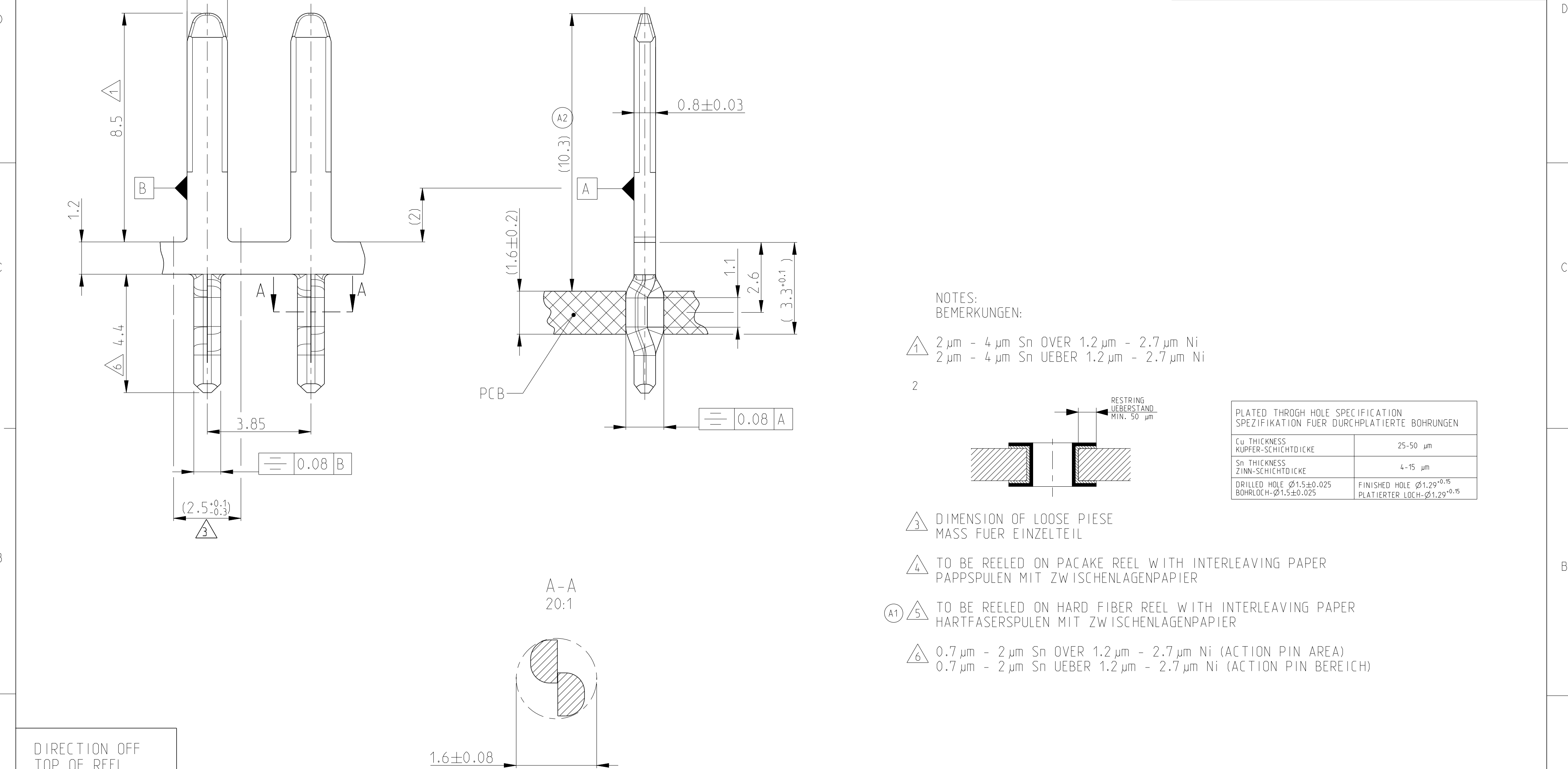


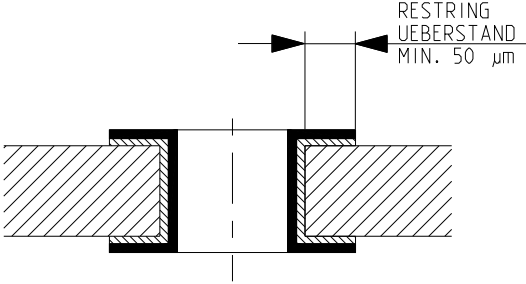
P	LTR	DESCRIPTION	DATE	DWN	APVD
	A1	Note 5 von Kunststoffspule auf Hartspule geaendert	14DEC2005	PNi	JRY
	A2	PCB verrutscht	07DEC2015	ST	PNi



NOTES:
BEMERKUNGEN:

1 2 µm - 4 µm Sn OVER 1.2 µm - 2.7 µm Ni
2 µm - 4 µm Sn UEBER 1.2 µm - 2.7 µm Ni

2



PLATED THROUGH HOLE SPECIFICATION SPEZIFIKATION FUER DURCHPLATIERTE BOHRUNGEN	
Cu THICKNESS KUPFER-SCHICHTDICKE	25-50 µm
Sn THICKNESS ZINN-SCHICHTDICKE	4-15 µm
DRILLED HOLE Ø1.5±0.025 BOHRLOCH-Ø1.5±0.025	FINISHED HOLE Ø1.29 ^{+0.15} _{-0.15} PLATIERTER LOCH-Ø1.29 ^{+0.15} _{-0.15}

3 DIMENSION OF LOOSE PIESE
MASS FUER EINZELTEIL

4 TO BE REELED ON PACAKE REEL WITH INTERLEAVING PAPER
PAPPSPULEN MIT ZWISCHENLAGENPAPIER

A1 5 TO BE REELED ON HARD FIBER REEL WITH INTERLEAVING PAPER
HARTFASERSPULEN MIT ZWISCHENLAGENPAPIER

6 0.7 µm - 2 µm Sn OVER 1.2 µm - 2.7 µm Ni (ACTION PIN AREA)
0.7 µm - 2 µm Sn UEBER 1.2 µm - 2.7 µm Ni (ACTION PIN BEREICH)

DIRECTION OFF
TOP OF REEL

1- -2
1- -3

4 5

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